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APPLICATION NO.	FILING DATE	FIRST NAMED INVENTOR	ATTORNEY DOCKET NO.	CONFIRMATION NO.	
10/774,115	02/06/2004	Glen C. Shepherd	Solectron 735	8375	
Robert Moll	7590 07/23/200		EXAMINER		
1173 St. Charle			DINH, T	DINH, TUAN T	
Los Altos, CA	94024		ART UNIT	PAPER NUMBER	
			2841		
			MAIL DATE	DELIVERY MODE	
			07/23/2008	PAPER	

Please find below and/or attached an Office communication concerning this application or proceeding.

The time period for reply, if any, is set in the attached communication.

	Application No.	Applicant(s)					
Office Action Occurrence	10/774,115	SHEPHERD ET AL.					
Office Action Summary	Examiner	Art Unit					
	Tuan T. Dinh	2841					
The MAILING DATE of this communication app Period for Reply	ears on the cover sheet with the c	orrespondence address					
A SHORTENED STATUTORY PERIOD FOR REPLY WHICHEVER IS LONGER, FROM THE MAILING DA  - Extensions of time may be available under the provisions of 37 CFR 1.13 after SIX (6) MONTHS from the mailing date of this communication.  - If NO period for reply is specified above, the maximum statutory period w  - Failure to reply within the set or extended period for reply will, by statute, Any reply received by the Office later than three months after the mailing earned patent term adjustment. See 37 CFR 1.704(b).	ATE OF THIS COMMUNICATION 16(a). In no event, however, may a reply be tim ill apply and will expire SIX (6) MONTHS from cause the application to become ABANDONE	Lely filed the mailing date of this communication. (35 U.S.C. § 133).					
Status							
1)⊠ Responsive to communication(s) filed on <u>06 Ma</u>	arch 2008						
,— · · · · · · · · · · · · · · · · · · ·	action is non-final.						
<i>,</i> —	, <del></del>						
	closed in accordance with the practice under <i>Ex parte Quayle</i> , 1935 C.D. 11, 453 O.G. 213.						
Disposition of Claims							
4)⊠ Claim(s) <u>1-35</u> is/are pending in the application.							
• • • • • • • • • • • • • • • • • • • •	4a) Of the above claim(s) <u>30-33 and 35</u> is/are withdrawn from consideration.						
5) Claim(s) is/are allowed.							
6)⊠ Claim(s) <u>1-29 and 34</u> is/are rejected.	<u>-                                    </u>						
7) Claim(s) is/are objected to.							
8) Claim(s) are subject to restriction and/or	election requirement.						
Application Papers							
9)☐ The specification is objected to by the Examiner.							
10)⊠ The drawing(s) filed on <i>06 March 2008</i> is/are: a)⊠ accepted or b)□ objected to by the Examiner.							
Applicant may not request that any objection to the drawing(s) be held in abeyance. See 37 CFR 1.85(a).							
Replacement drawing sheet(s) including the correction is required if the drawing(s) is objected to. See 37 CFR 1.121(d).							
11)☐ The oath or declaration is objected to by the Ex		, ,					
Priority under 35 U.S.C. § 119							
12) Acknowledgment is made of a claim for foreign	priority under 35 LLS C & 119(a)	-(d) or (f)					
a) ☐ All b) ☐ Some * c) ☐ None of:	priority under 35 0.5.6. § 115(a)	-(d) 01 (1).					
1. Certified copies of the priority documents	s have been received						
3. Copies of the certified copies of the prior							
application from the International Bureau	•	a in time i tational Glage					
* See the attached detailed Office action for a list of the certified copies not received.							
	·						
Attachmont(s)							
Attachment(s)  1) X Notice of References Cited (PTO-892)	4) Interview Summary	(PTO-413)					
2) Notice of Traftsperson's Patent Drawing Review (PTO-948)	Paper No(s)/Mail Da	ite					
3) Information Disclosure Statement(s) (PTO/SB/08)	5) Notice of Informal P	atent Application					
Paper No(s)/Mail Date	6) [ Other:						

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## **DETAILED ACTION**

## Claim Rejections - 35 USC § 112

- 1. The following is a quotation of the second paragraph of 35 U.S.C. 112:
  - The specification shall conclude with one or more claims particularly pointing out and distinctly claiming the subject matter which the applicant regards as his invention.
- 2. Claims 11 and 15 are rejected under 35 U.S.C. 112, second paragraph, as being indefinite for failing to particularly point out and distinctly claim the subject matter which applicant regards as the invention.

Regarding claims 11, and 25, lines 1-3 are unclear. The phrase of "the substrate...further comprising a surface mounted (SMT) component electrically connected to the conductive pad" is not understood because as claimed in claims 1 and 14 and also in figures 3-4 there is "a SMT component (as in claimed 1 and 14) is electrically connected to the pad. Why two components can connected to the conductive pad.? It is contradiction. Please, clarify the claims.

## Claim Rejections - 35 USC § 103

- 3. The following is a quotation of 35 U.S.C. 103(a) which forms the basis for all obviousness rejections set forth in this Office action:
  - (a) A patent may not be obtained though the invention is not identically disclosed or described as set forth in section 102 of this title, if the differences between the subject matter sought to be patented and the prior art are such that the subject matter as a whole would have been obvious at the time the invention was made to a person having ordinary skill in the art to which said subject matter pertains. Patentability shall not be negatived by the manner in which the invention was made.

4. Claims 1-2, 9-15, and 22-29 are rejected under 35 U.S.C. 103(a) as being unpatentable over Lauffer et al. (U.S. Patent 5,811,736) in view of Dishongh ('31) as in the record.

As to claims 1-2, 11-13, Lauffer et al. discloses a PCB (10) or a part of BGA package footprint having a substrate (12) as shown in figures 4-6, the substrate comprising:

A SMT component (46) having terminals (44), see figure 6 mounted on a conductive layer (20) of the substrate (12), a conductive pad (138) having a trace (139), and a solder resist/mask (53), the solder mask (53) covers a part of the pad (the mask mounted on the trace (139)), the component (46) connected to the substrate by a solder (55), the solder formed between the terminal (44) of the component (46) and the solder mask (53).

Lauffer et al. does not disclose the solder mask surround a plated via, and the plated via connected to the trace.

Dshough discloses a substrate (120) having a solder mask (160) surrounding a plated via (130 having plated 132) connected to conductive layers (not show, but the PCB 120 having plurality of conductor layers, see column 1, lines 30-32), a conductive pad (122, 124) with a conductive trace connected to the plated via (130).

It would have been obvious to one having ordinary skill in the art at the time the invention was made to have a teaching of Dshough employed in the substrate or PCB (10) of Lauffer in order to protect the solder slash and prevent short circuit when the component connected to the substrate by the solder.

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As to claims 14-15, 25, 26, Dishongh et al. discloses a PCB (10) or a part of footprint as shown in figures 4-6, comprising: a SMT component (46) having first and second terminals (44) soldered (55) and mounted on substrate (12), first and second conductive layers (20), first and second solder masks (53, figure 6 shows the solder mask 55 formed on the right side of the substrate 12); first and second conductive pads (138) each with a conductive trace (139), the solder mask (53) cover the solder (55) at the first and second terminals (44).

Dshough discloses a substrate (120) having a solder mask (160) surrounding a plated via (130 having plated 132) connected to conductive layers (not show, but the PCB 120 having plurality of conductor layers, see column 1, lines 30-32), a conductive pad (122, 124) with a conductive trace connected to the plated via (130).

It would have been obvious to one having ordinary skill in the art at the time the invention was made to have a teaching of Dshough employed in the substrate or PCB (10) of Lauffer in order to protect the solder slash and prevent short circuit when the component connected to the substrate by the solder.

As to claims 3, 5 and 16, 18, Lauffer as modified by Dshough discloses the pads (138) each having first and second arms and a body, see figure 5.

As to claims 4, 6 and 17, 19, Lauffer as modified by Dshough show the first and second arms are symmetrically (figure 5) and disposed on the substrate with respect to the plated via.

As to claims 7-8 and 20-21, Lauffer as modified by Dshough discloses the pad (138) including a T-shaped structure (see figure 5) having arms being symmetrically disposed on the substrate (12).

As to claims 9-10, 22-24, and 29, Lauffer as modified by Dshough discloses the solder mask(s) being a keyhole or ring shaped partially covered the substrate.

As to claim 26, Lauffer as modified by Dshough discloses a separator along the substrate between the first and second solder masks (53) defined a length of the SMT component (46) soldered.

As to claim 34, Lauffer as modified by Dshough disclose the first conductive pad (138) extended beyond the terminal of the component (46), see figure 6 at maximum distance (end at the solder mask 53) to reduce a solder vicking.

## Response to Arguments

Applicant's arguments with respect to claims 1-29 and 34 have been considered but are most in view of the new ground(s) of rejection.

Applicant's amendment necessitated the new ground(s) of rejection presented in this Office action. Accordingly, **THIS ACTION IS MADE FINAL**. See MPEP § 706.07(a). Applicant is reminded of the extension of time policy as set forth in 37 CFR 1.136(a).

A shortened statutory period for reply to this final action is set to expire THREE MONTHS from the mailing date of this action. In the event a first reply is filed within TWO MONTHS of the mailing date of this final action and the advisory action is not

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mailed until after the end of the THREE-MONTH shortened statutory period, then the shortened statutory period will expire on the date the advisory action is mailed, and any extension fee pursuant to 37 CFR 1.136(a) will be calculated from the mailing date of the advisory action. In no event, however, will the statutory period for reply expire later than SIX MONTHS from the date of this final action.

Any inquiry concerning this communication or earlier communications from the examiner should be directed to Tuan T. Dinh whose telephone number is 571-272-1929. The examiner can normally be reached on M-F.

If attempts to reach the examiner by telephone are unsuccessful, the examiner's supervisor, Reichard Dean can be reached on 571-272-1984. The fax phone number for the organization where this application or proceeding is assigned is 571-273-8300.

Information regarding the status of an application may be obtained from the Patent Application Information Retrieval (PAIR) system. Status information for published applications may be obtained from either Private PAIR or Public PAIR. Status information for unpublished applications is available through Private PAIR only. For more information about the PAIR system, see http://pair-direct.uspto.gov. Should you have questions on access to the Private PAIR system, contact the Electronic Business Center (EBC) at 866-217-9197 (toll-free). If you would like assistance from a USPTO Customer Service Representative or access to the automated information system, call 800-786-9199 (IN USA OR CANADA) or 571-272-1000.

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Primary Examiner, Art Unit 2841.